

* No covering letter.

RTmp's copy

9703307-0



PCT

WORLD INTELLECTUAL PROPERTY ORGANIZATION
International Bureau

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶: H05K 9/00	A1	(11) International Publication Number: WO 96/28007 (43) International Publication Date: 12 September 1996 (12.09.96)
(21) International Application Number: PCT/US96/02818 (22) International Filing Date: 1 March 1996 (01.03.96) (30) Priority Data: 08/398,476 3 March 1995 (03.03.95) US (71) Applicant: PARKER-HANNIFIN CORPORATION [US/US]; 17325 Euclid Avenue, Cleveland, OH 44112 (US). (72) Inventor: SALVI, Joseph, A., Jr.; Apartment 177, 6551 Warner Avenue, Huntington Beach, CA 92647 (US). (74) Agent: MOLNAR, John, A., Jr.; Parker-Hannifin Corporation, 17325 Euclid Avenue, Cleveland, OH 44112 (US).		(81) Designated States: AT, BR, CA, CN, FI, JP, MX, NO, RU, SG, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>
(54) Title: SHIELDED ENCLOSURE FOR ELECTRONICS (57) Abstract An EMI/RFI shielded cover plate assembly for an electronics enclosure (10) includes a cover plate (18; 20) having a major surface area (24) with outwardly-projecting walls or flanges defining interface locations with the underlying enclosure. A shielding compound (22) is provided across the entire cover plate (18; 20) including the walls (25) or flanges. The shielding compound (22) is disposed in a relatively thin layer across the major surface area (24) of the cover plate (18; 20) for EMI/RFI shielding, and in a thicker layer at the interface locations (25; 27) to provide a gasket-like response for environmentally sealing the cover plate (18; 20) assembly to the underlying enclosure and for thermal transfer and electrical continuity. The shielding compound (22) can be compression molded with the cover plate (18; 20). The shielded cover plate assembly provides a simple and economical method for providing an EMI/RFI shield and a gasket from a single shielding compound.		